

SN54LVT162240, SN74LVT162240 3.3-V ABT 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS719 – JULY 2000

- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation**
- **Output Ports Have Equivalent 22-Ω Series Resistors, So No External Resistors Are Required**
- **Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Support Unregulated Battery Operation Down to 2.7 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$**
- **I_{off} and Power-Up 3-State Support Hot Insertion**
- **Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- **Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings**

SN54LVT162240 . . . WD PACKAGE
SN74LVT162240 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)

$\overline{1OE}$	1	48	$2\overline{OE}$
1Y1	2	47	1A1
1Y2	3	46	1A2
GND	4	45	GND
1Y3	5	44	1A3
1Y4	6	43	1A4
V_{CC}	7	42	V_{CC}
2Y1	8	41	2A1
2Y2	9	40	2A2
GND	10	39	GND
2Y3	11	38	2A3
2Y4	12	37	2A4
3Y1	13	36	3A1
3Y2	14	35	3A2
GND	15	34	GND
3Y3	16	33	3A3
3Y4	17	32	3A4
V_{CC}	18	31	V_{CC}
4Y1	19	30	4A1
4Y2	20	29	4A2
GND	21	28	GND
4Y3	22	27	4A3
4Y4	23	26	4A4
$4\overline{OE}$	24	25	$3\overline{OE}$

NOTE: For tape and reel order entry:
The DGG package is abbreviated to GR, and
the DGV package is abbreviated to VR.

description

The 'LVT162240 devices are 16-bit buffers/drivers designed specifically for low-voltage (3.3-V) V_{CC} operation and to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. They have the capability to provide a TTL interface to a 5-V system environment.

These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer and provide inverting outputs and symmetrical active-low output-enable (\overline{OE}) inputs.

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SN54LVT162240, SN74LVT162240

3.3-V ABT 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCBS719 – JULY 2000

description (continued)

The outputs, which are designed to source or sink up to 12 mA, include equivalent 22- Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVT162240 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74LVT162240 is characterized for operation from -40°C to 85°C .

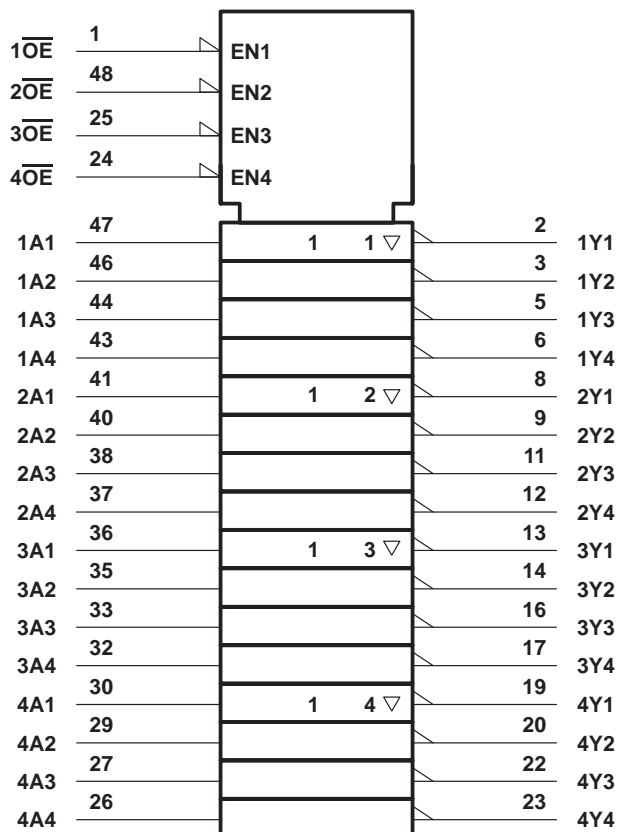
FUNCTION TABLE
(each 4-bit buffer/driver)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	L
L	L	H
H	X	Z

SN54LVT162240, SN74LVT162240
3.3-V ABT 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

SCBS719 – JULY 2000

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

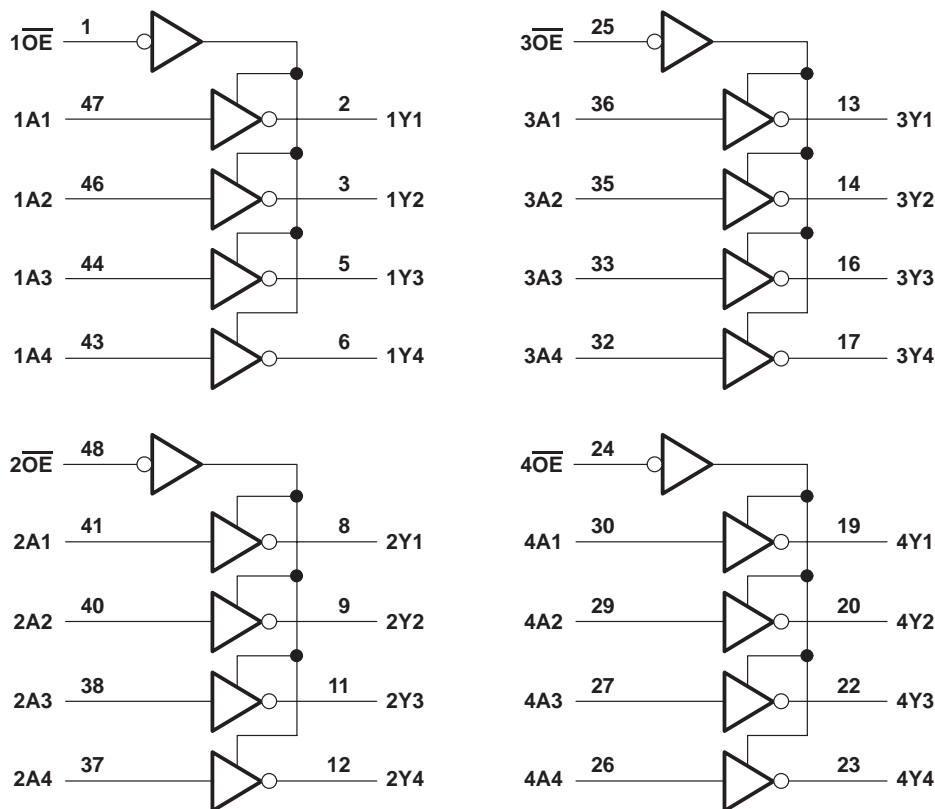
SN54LVT162240, SN74LVT162240

3.3-V ABT 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

SCBS719 – JULY 2000

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O	30 mA
Current into any output in the high state, I_O (see Note 2)	30 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The package thermal impedance is calculated in accordance with JESD 51.

SN54LVT162240, SN74LVT162240
3.3-V ABT 16-BIT BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS
SCBS719 – JULY 2000

recommended operating conditions (see Note 4)

			SN54LVT162240		SN74LVT162240		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V _{IH}	High-level input voltage		2		2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
V _I	Input voltage			5.5		5.5	V
I _{OH}	High-level output current			–12		–12	mA
I _{OL}	Low-level output current			12		12	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN54LVT162240			SN74LVT162240			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}		V _{CC} = 2.7 V, I _I = –18 mA			–1.2			–1.2	V
V _{OH}		V _{CC} = 3 V, I _{OH} = –12 mA	2			2			V
V _{OL}		V _{CC} = 3 V, I _{OL} = 12 mA			0.8			0.8	V
I _I		V _{CC} = 0 or 3.6 V, V _I = 5.5 V			10			10	μA
	Control inputs	V _{CC} = 3.6 V, V _I = V _{CC} or GND			±1			±1	
	Data inputs	V _{CC} = 3.6 V, V _I = V _{CC}			1			1	
		V _I = 0			–5			–5	
I _{off}		V _{CC} = 0, V _I or V _O = 0 to 4.5 V						±100	μA
I _{OZH}		V _{CC} = 3.6 V, V _O = 3 V			5			5	μA
I _{OZL}		V _{CC} = 3.6 V, V _O = 0.5 V			–5			–5	μA
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, OE = don't care			±100*			±100	μA
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, OE = don't care			±100*			±100	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND			0.19			0.19	mA
		Outputs high			5			5	
		Outputs disabled			0.19			0.19	
ΔI _{CC} ‡		V _{CC} = 3 V to 3.6 V, One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND			0.2			0.2	mA
C _i		V _I = 3 V or 0			4			4	pF
C _o		V _O = 3 V or 0			9			9	pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54LVT162240, SN74LVT162240

3.3-V ABT 16-BIT BUFFERS/DRIVERS

WITH 3-STATE OUTPUTS

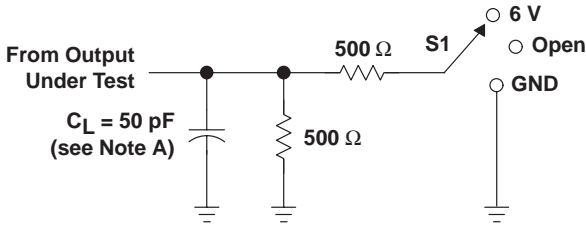
SCBS719 – JULY 2000

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

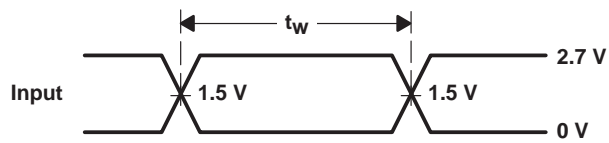
PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54LVT162240				SN74LVT162240				UNIT	
			$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$			$V_{CC} = 2.7\text{ V}$		
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN		MAX
tPLH	A	Y	1	4.2		5	1	2.5	4		4.6	ns
tPHL			1	4.2		5	1	2.9	4		4.6	
tPZH	\overline{OE}	Y	1	5		5.5	1	2.8	4.8		5.7	ns
tPZL			1	4.9		5.1	1	2.8	4.7		4.9	
tPHZ	\overline{OE}	Y	1.9	4.9		5.4	2	3.5	4.7		5.2	ns
tPLZ			1.9	4.7		4.8	2	3.4	4.5		4.5	
t _{sk(o)}									0.5			ns

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

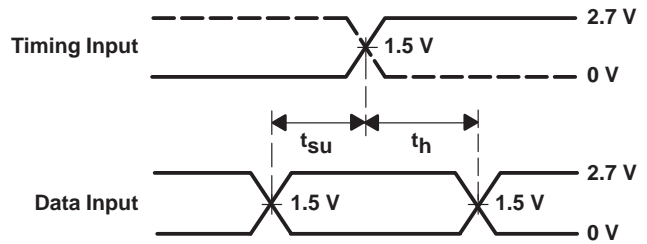
PARAMETER MEASUREMENT INFORMATION



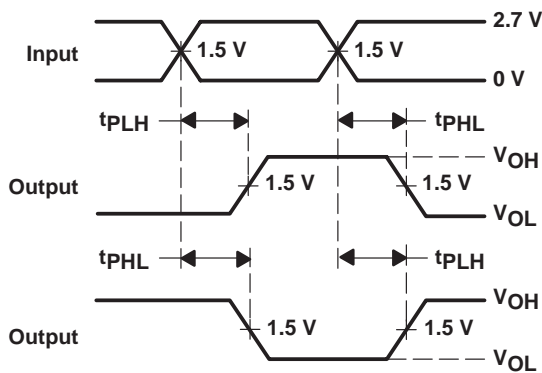
LOAD CIRCUIT



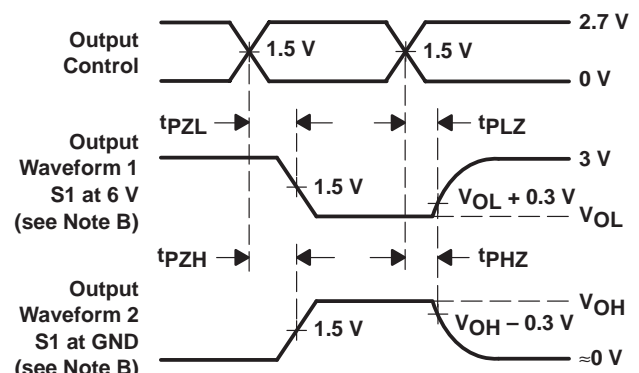
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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